



Power MOSFETS

DATASHEET

LM1AB50PAQ8A

P-Channel
Enhancement Mode MOSFET

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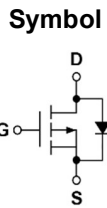
Quality Management Systems

ISO 9001:2015 Certificate

LM1AB50PAQ8A

P-Channel Enhancement Mode MOSFET

Pin Description



Product Summary

Symbol	P-Channel	Unit
V_{DS}	-100	V
$R_{DS(ON)-Max}$	260	mΩ
ID	-6	A

Feature

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

Applications

- DC/DC Converters
- Motor Control
- Uninterrupted Power Supply

Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM1AB50PAQ8A	SOP-8L	Tape & Reel	3000 / Tape & Reel	1AB50 □□□□□□

Note : □□□□□□ = Lot Code

Absolute Maximum Ratings (T_J=25°C Unless Otherwise Noted)

Symbol	Parameter	P-Channel	Unit
V_{DS}	Drain-Source Voltage	-100	V
V_{GS}	Gate-Source Voltage	±20	V
T_J	Maximum Junction Temperature	150	°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
I_S	Diode Continuous Forward Current	$T_A=25^\circ\text{C}$ -1.3	A
$I_{DM}^{(1)}$	Pulse Drain Current Tested	$T_A=25^\circ\text{C}$ -6	A
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$ $T_A=70^\circ\text{C}$ -2.4 -1.9	A
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$ $T_A=70^\circ\text{C}$ 1.5 0.9	W
$I_{AS}^{(2)}$	Avalanche Current, Single pulse	L=0.1mH L=0.5mH -22 -14	A
$E_{AS}^{(2)}$	Avalanche Energy, Single pulse	L=0.1mH L=0.5mH 24 9.8	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{(3)}$	Thermal Resistance-Junction to Ambient	$t \leq 10s$ 43 Steady State 85	°C/W °C/W

Note ① : Max. current is limited by junction temperature

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz

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P-Channel Electrical Characteristics (T_J=25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Electrical Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250uA	-100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-80V, V _{GS} =0V	-	-	-1	uA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250uA	-1	-2	-3	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ④	Drain-Source On-state Resistance	V _{GS} =-10V, I _{DS} =-1A	-	220	260	mΩ
		V _{GS} =-4.5V, I _{DS} =-0.5A		230	290	
gfs	Forward Transconductance	V _{DS} =-5V, I _{DS} =-0.5A	-	3.4	-	S
Dynamic Characteristics ⑤						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, Freq.=1MHz	-	18	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-50V, Freq.=1MHz	-	1499	-	pF
C _{oss}	Output Capacitance		-	35	-	
C _{rss}	Reverse Transfer Capacitance		-	26	-	
td(ON)	Turn-on Delay Time	V _{GS} =-10V, V _{DS} =-30V, I _D =-1A, R _{GEN} =1Ω	-	6.7	-	nS
t _r	Turn-on Rise Time		-	4.2	-	
t _{d(OFF)}	Turn-off Delay Time		-	103	-	
t _f	Turn-off Fall Time		-	35	-	
Q _g	Total Gate Charge	V _{GS} =-4.5V, V _{DS} =-50V I _D =-1A	-	12.6	-	nC
Q _g	Total Gate Charge	V _{GS} =-10V, V _{DS} =-50V, I _D =-1A	-	27.6	-	
Q _{gs}	Gate-Source Charge		-	5.5	-	
Q _{gd}	Gate-Drain Charge		-	3.6	-	
Source-Drain Characteristics						
V _{SD} ④	Diode Forward Voltage	I _{SD} =-0.5A, V _{GS} =0V	-	0.75	1.1	V
t _{rr}	Reverse Recovery Time	I _F =-1A, V _R =-50V	-	20.5	-	nS
Q _{rr}	Reverse Recovery Charge	dI _F /dt=100A/μs	-	17.7	-	nC

Note ④ : Pulse test (pulse width≤300us, duty cycle≤2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

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P-Channel Typical Characteristics

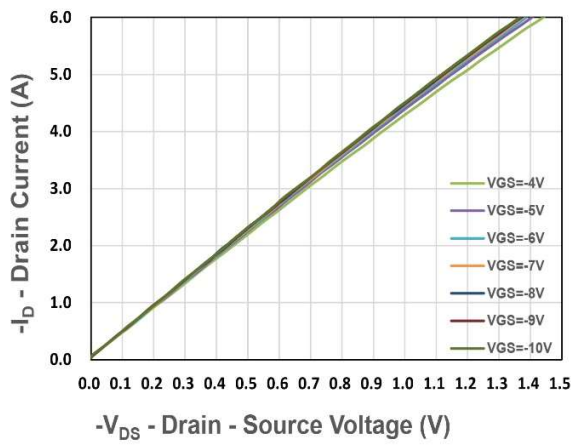


Figure 1. Output Characteristics

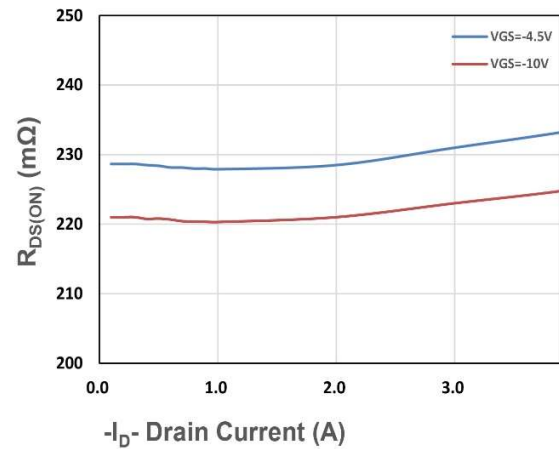


Figure 2. On-Resistance vs. ID

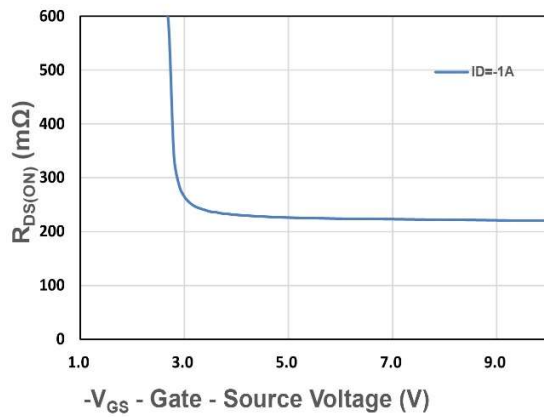


Figure 3. On-Resistance vs. VGS

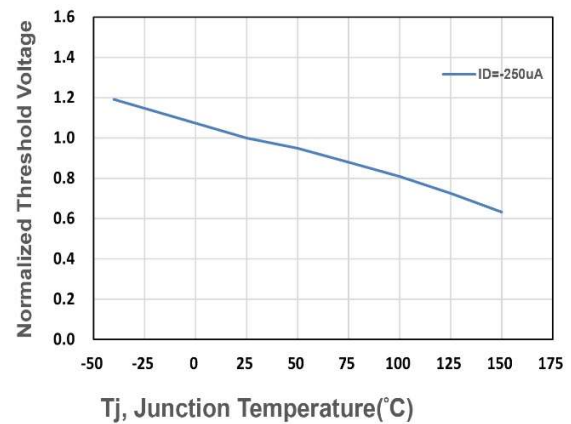


Figure 4. Gate Threshold Voltage

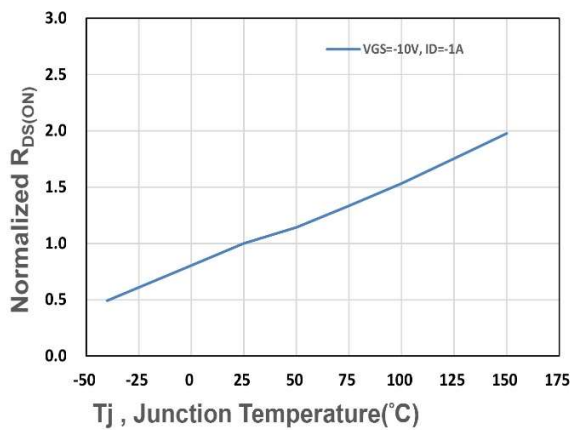


Figure 5. Drain-Source On Resistance

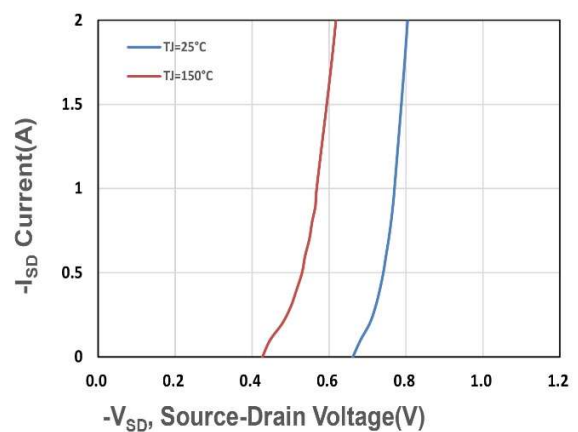
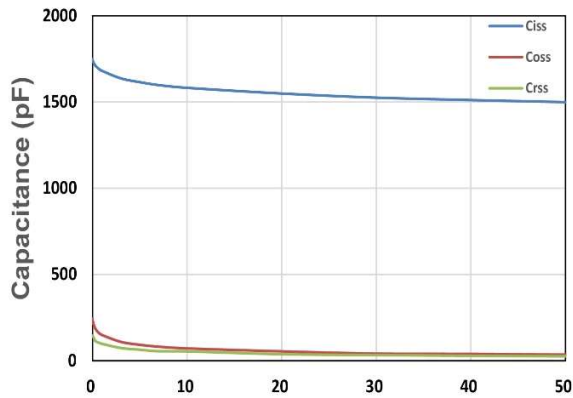
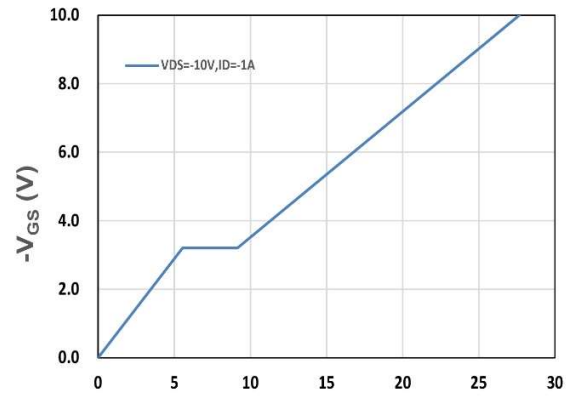


Figure 6. Source-Drain Diode Forward

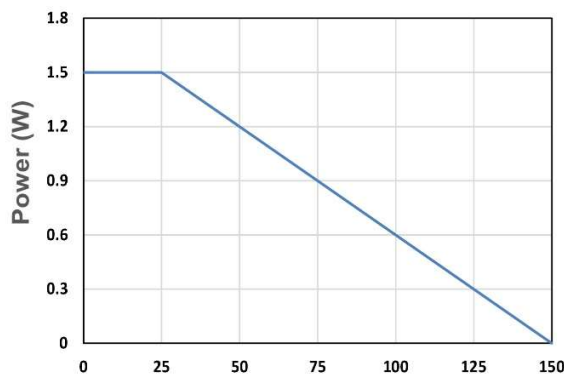
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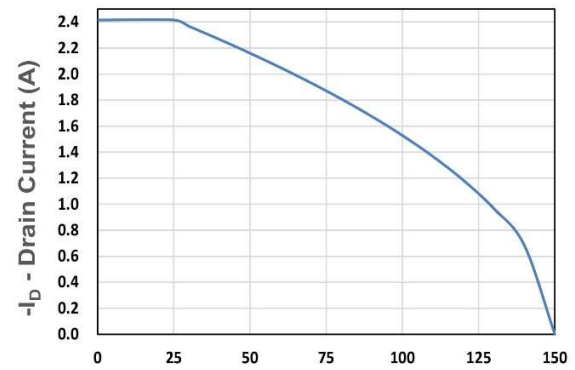
$-V_{DS}$ - Drain - Source Voltage (V)
Figure 7. Capacitance



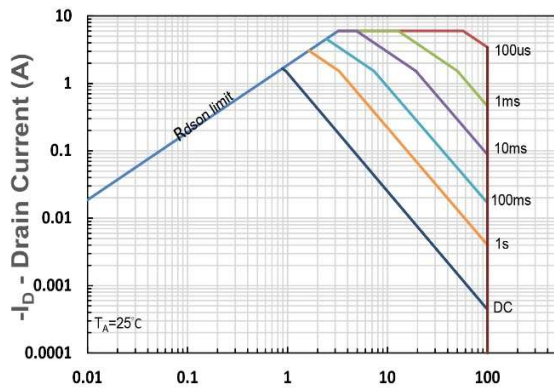
Q_g , Total Gate Charge (nC)
Figure 8. Gate Charge Characteristics



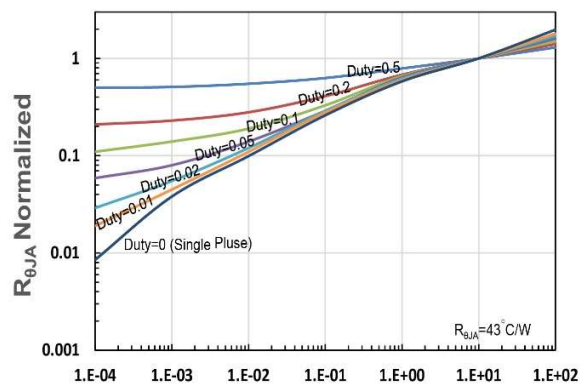
T_A - Ambient Temperature (°C)
Figure 9. Power Dissipation



T_A - Ambient Temperature (°C)
Figure 10. Drain Current



$-V_{DS}$ - Drain-Source Voltage (V)
Figure 11. Safe Operating Area



t_1 , Square Wave Pulse Duration(s)
Figure 12. $R_{\theta JA}$ Transient Thermal Impedance